

IRPS 2015

IEEE International Reliability Physics Symposium

Monday Tutorial Presentations

April 20, 2015

M1.1: Wafer Level Functional SRAM Intrinsic Reliability Testing

M1.2: Advanced Chip-Package Integration

M1.3: FA Methods and Failure Signatures

M2.1: The Resilience Wall: Cross-Layer Solutions

M2.2: Reliability Aspects of 650V GaN-on-Si Power Devices

M2.3: A Review of ReRAM Technology for Improving Reliability

M3.1: System Modeling Reliability & Availability

M3.2a: Sample Size Statistics for Consumer Electronics Reliability Tests

M3.2b: Statistics in Reliability and Return Analysis

M3.3: Self-Heating Effects (SHE), Impacts and Solutions

